



Final Product Change Notification

201710041F01

Issue Date: 17-Nov-2017

Effective Date: 15-Feb-2018

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

0.25um Technology 10x10LQFP Assembly Site Expansion to TongFu Microelectronics Co. LTD

Details of this Change

NXP Semiconductors is announcing the assembly site expansion for 0.25um technology 10x10LQFP packages from current NXP assembly, Tian Jin, China (ATTJ) Assembly Facility to the TongFu Microelectronics Co. LTD, Nantong, China (TFME) Facility.

Why do we Implement this Change

Qualification of the TongFu Microelectronics Co. LTD, Nantong, China (TFME) Assembly Facility ensures manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Refer to Remarks section for details.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 15-Feb-2018

Impact

There is no change to product fit, function, or reliability.
For Form, refer to visual comparison document attached.

Disposition of Old Products

NXP will reserve the right to ship from any location based on market demand situation.

Additional information

Self qualification: [view online](#)
Additional documents: [view online](#)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 17-Dec-2017.

Remarks

The assembly site is reflected in the package trace code.
The format for the NXP standard trace code:
LQFP64: AWLYYWWZ or ATWLYYWWZ or ATWLYWWZ
LQFP44: AWLYYWWZ
A=Assembly Location, T=Test Location, WL=Wafer Lot, YYWW=Date Code.
The marking for NXP-ATTJ is A=CT.
The marking for TFME is A=XN.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Kan Liu
Position	Product Engineer
e-mail address	mailto:kan.liu@nxp.com?subject=Support

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.